Sn-3.0Ag-0.5Cu Standard Lead-free Solder Paste

Reduce the amount of solder paste waste due to stable viscosity

HVS series

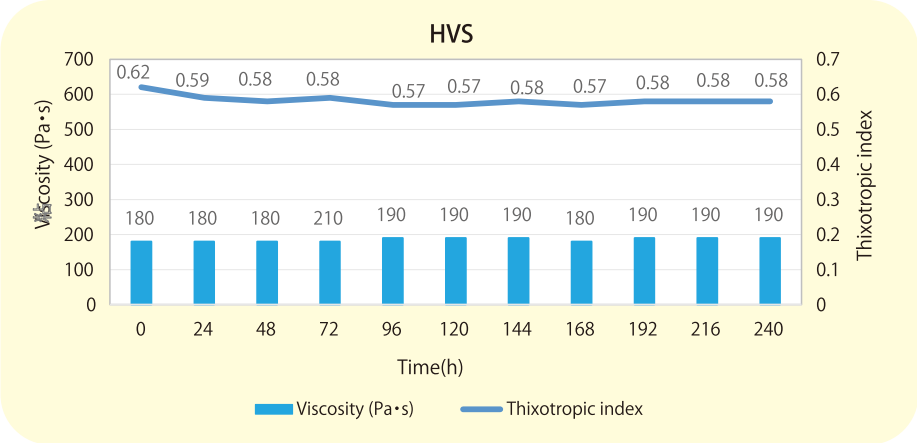
Product lineup

Product name	Alloy composition	Melting point※
PS31BR-600A-HVS	Sn-3.0Ag-0.5Cu	219℃

※JIS Z 3198-1

Enable 10-days consecutive production

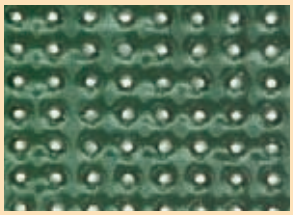
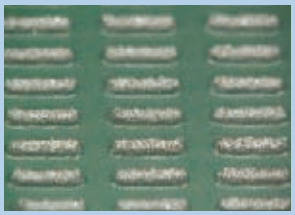
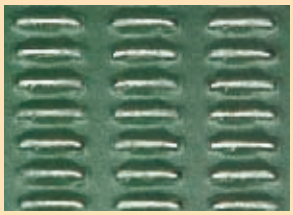
Viscosity change at the time of continuous printing



Test condition

- 50% of paste was replaced with new paste, every 12 hours

Printing & Wettability after continuous printing(240hours)

	Printing	Wettability
Φ0.25mm land		
0.18mmx1.0mm land		

Test condition

- Reflow condition : Air
- Print thickness : 120μm

Realize the reduction of waste paste amount with excellent solderability